

Bill of Materials

TI DESIGNS TIDA-00220
Human Proximity Detection for System Wakeup / Interrupt

Designator	Description	Manufacturer	PartNumber	Quantity
!PCB1	Printed Circuit Board	Any	ISE4010	1
BL1	LED Backlight, White	Electronic Assembly	EA LED55X46-W	1
C1, C34	CAP, CERM, 2.2uF, 10V, +/-10%, X7R, 0603	MuRata	GRM188R71A225KE15D	2
C4	CAP, CERM, 2.2 uF, 10 V, +/- 10%, X7R, 0603	MuRata	GRM188R71A225KE15D	1
C5, C6	CAP, CERM, 10 uF, 6.3 V, +/- 20%, X7R, 0805	TDK	C2012X7R0J106M125AB	2
C7	CAP, CERM, 1000pF, 2000V, +/-10%, X7R, 1210	Kemet	C1210C102KGRACTU	1
C9, C16, C18, C19, C20, C21, C22, C23, C26, C28, C31, C32, C33	CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603	TDK	C1608X7R1C105K	13
C10, C15, C17	CAP, CERM, 2200pF, 50V, +/-10%, X7R, 0402	TDK	C1005X7R1H222K	3
C11, C14, C27	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402	MuRata	GRM155R71C104KA88D	3
C29, C30	CAP, CERM, 82 pF, 50 V, +/- 5%, C0G/NP0, 0402	MuRata	GRM1555C1H820JA01D	2
C35	CAP, CERM, 1uF, 50V, +/-10%, X7R, 0603	Taiyo Yuden	UMK107AB7105KA-T	1
C36	CAP, CERM, 0.01uF, 10V, +/-10%, X7R, 0201	MuRata	GRM033R71A103KA01D	1
D1	Diode, Zener, 5.6V, 550 mW, SMB	ON Semiconductor	1SMB5919BT3G	1
D2, D3	LED, Green, SMD	Rohm	SML-P12PTT86	2
D4	Diode, Schottky, 40V, 0.25A, SOD-523	ON Semiconductor	NSR0240V2T1G	1
D5	Diode, Schottky, 5V, 0.03A, SOD-323	Toshiba	1SS315TPH3F	1
D6	Diode, TVS, Bi, 6 V, 600 W, SMB	Littelfuse	SMBJ6.0CA	1
H1, H2, H5, H7, H8, H11, H13	Standoff, Hex, 0.5"L #4-40 Nylon	Keystone	1902C	7
H3, H4, H6, H9, H10, H12, H14	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener Supply	NY PMS 440 0025 PH	7
J1	Connector, Receptacle, Mini-USB Type B, R/A, Top Mount SMT	TE Connectivity	1734035-2	1
J2	Header, 100mil, 2x1, Tin plated, TH	Molex	90120-0122	1
J3	Header, 100mil, 2x1, Tin, TH	Molex	90120-0122	1
J4	Header (shrouded), 100 mil, 7x2, Gold plated, TH	Sullins Connector Solutio	SBH11-PBPC-D07-ST-BK	1
J5	Header, 100mil, 4x2, Gold, TH	Samtec	TSW-104-07-G-D	1
J6, J7	Straight Low Profile Header, 10x2 Position, 1.27 mm Pitch, SMT	Samtec	TFM-110-02-L-D-A	2
J9	Header, 3x1, 100mil, SMT	Mill-Max	800-10-003-10-001000	1
L1, L3, L5	1.5A Ferrite Bead, 330 ohm @ 100MHz, SMD	MuRata	BLM18SG331TN1D	3
L4	Inductor, Shielded, Ferrite, 10uH, 0.47A, 0.24 ohm, SMD	TDK	VLF252015MT-100M	1
LBL1	Thermal Transfer Printable Labels, 0.650" W x 0.200" H, 10,000 per roll	Brady	THT-14-423-10	1
Q1, Q2	MOSFET, N-CH, 50V, 0.22A, SOT-23	Fairchild Semiconductor	BSS138	2
R1, R8, R16, R17, R18, R19, R20, R21, R22, R23, R25, R27, R28, R29	RES, 0 ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04020000Z0ED	14
R2, R3	RES, 4.99k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04024K99FKED	2

Designator	Description	Manufacturer	PartNumber	Quantity
R4, R5, R6	RES, 47.5k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060347K5FKEA	3
R7, R30	RES, 0, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04020000Z0ED	2
R9, R10	RES, 221 ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW0402221RFKED	2
R11, R12	RES, 38.3 k, 1%, 0.063 W, 0402	Vishay-Dale	CRCW040238K3FKED	2
R26	RES, 10.0k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040210K0FKED	1
R31, R34, R35, R38, R39, R42, R43, R46	RES, 0 ohm, 5%, 1W, 2512	Vishay-Dale	CRCW25120000Z0EG	8
S1, S2, S3	Switch, Tactile, SPST-NO, 0.05A, 12V, SMT	TE Connectivity	4-1437565-1	3
SH-J1, SH- J2, SH-J4, SH-J5	Shunt, 2mm, Gold plated, Black	Samtec	2SN-BK-G	4
SH-J3	Shunt, 100mil, Gold plated, Black	TE Connectivity	881545-2	1
TP1, TP3	Test Point, Miniature, Red, TH	Keystone	5000	2
TP2, TP13, TP14, TP15, TP16	Test Point, Miniature, Black, TH	Keystone	5001	5
TP4, TP5, TP11, TP12	Test Point, Miniature, Yellow, TH	Keystone	5004	4
TP6, TP7, TP8, TP9, TP10	Test Point, Miniature, Orange, TH	Keystone	5003	5
U1	ULTRA LOW-NOISE, 250-mA LINEAR REGULATOR FOR RF AND ANALOG CIRCUITS REQUIRES NO BYPASS CAPACITOR, DBV0005A	Texas Instruments	LP5907MFX-3.3/NOPB	1
U3	Mixed Signal Microcontroller, RGZ0048B	Texas Instruments	MSP430FR5969IRGZ	1
U4	Module, 128x64-pixel graphics display	Electronic Assembly	EA DOGM128W-6	1
U5, U6, U8,	ESD in 0402 Package with 10 pF Capacitance and 6 V	Texas Instruments	TPD1E10B06DPYR	6
U7	4-Channel Capacitance-to-Digital Converter for Capacitive Sensing Solutions, DSC0010B	Texas Instruments	FDC1004DSC	1
U12	LM3630A High-Efficiency Dual-String White LED Driver, YFQ0012AKAR	Texas Instruments	LM3630ATME	1
U13	High-Accuracy, Low-Power, Digital Temperature Sensor With SMBus(TM)/Two-Wire Serial Interface, DRL0006A	Texas Instruments	TMP112AIDRL	1
C2, C3	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Used in BOM report	Used in BOM report	0
C24, C25	CAP, CERM, 18pF, 100V, +/-5%, C0G/NP0, 0603	MuRata	GRM1885C2A180JA01D	0
FID1, FID2, FID3, FID4, FID5, FID6	Fiducial mark. There is nothing to buy or mount.	N/A	N/A	0
R13, R14, R15, R24	RES, 0 ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04020000Z0ED	0
Y1	Crystal, 8MHz, 18pF, SMD	Abracon Corporation	ABLS-8.000MHZ-B4-T	0

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